

## EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	8048	(257/750,758,759,779,782).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/02/07 11:40
L2	772	L1 and (insulate insulating insulation) near3 (resin polymer organic plastic "thermo-plastic")	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/02/07 11:40
L3	461	L2 and (wiring lead "wiring pattern") near3 (layer board pattern)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/02/07 11:40
L4	293	L3 and @ad<"20031006"	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/02/07 11:40
L5	15	L4 and (underfill)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	OFF	2008/02/07 11:40
L6	15	L5 and (chip die)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/02/07 11:40
L7	11	L6 and (pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT	OR	ON	2008/02/07 11:40

2/7/2008 11:40:41 AM

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